



SRM
INSTITUTE OF SCIENCE & TECHNOLOGY
(Deemed to be University u/s 3 of UGC Act, 1956)

Department of Mechanical Engineering
College of Engineering and Technology
SRM Institute of Science and Technology
SRM Nagar, Kattankulathur-603203

Summer Internship 2025: ANSYS ICEPAK

Organized by the Center of Excellence for Electronic Cooling and CFD Simulation

Unleash Your Potential in Computational Fluid Dynamics (CFD) and Electronic Cooling

Duration: One week

Mode: On-Campus

Venue: Center of Excellence for Electronic Cooling and CFD Simulation Lab, SRM Institute of Science and Technology, BEL 407, Basic Engineering Lab, Third Floor, Annexure Campus, Kattankulathur, Chennai - 603203, Tamil Nadu, India.

Batch: 12 May 2025, 19 May 2025, 26 May 2025, 2 June 2025, 9 June 2025, 16 June 2025, 23 June 2025, 30 June 2025, 7 July 2025, 14 July 2025, 21 July 2025

About the Internship

The ANSYS ICEPAK Winter Internship provides hands-on training and exposure to state-of-the-art computational tools for thermal and fluid flow analysis. This program is designed to bridge the gap between academia and industry by equipping students with practical skills in electronic cooling simulation, a critical area in thermal management systems.

Key Features

- Practical Training: Learn to simulate thermal management and airflow designs for electronic components.
- Expert Guidance: Mentorship by experienced faculty and industry professionals.
- Project-Based Learning: Work on real-world projects and case studies.
- Certification: Get certified by the Center of Excellence for Electronic Cooling.

Topics Covered

- 1. Introduction to ANSYS ICEPAK**
 - Overview and applications
 - User interface and basic workflow
- 2. Heat Transfer Principles in Electronics**
 - Conduction, convection, and radiation modeling
 - Basics of thermal resistance networks
- 3. Thermal and Fluid Flow Simulation**
 - Setting up electronic cooling simulations
 - Meshing techniques and solver settings
- 4. Advanced Modeling Techniques**
 - PCB thermal analysis
 - Forced and natural convection in electronic systems
- 5. Case Studies and Industry Applications**
 - Thermal design optimization of heat sinks
 - Airflow analysis for data centers and electronic devices

Who Can Apply?

Undergraduate and postgraduate students in Engineering and pursuing engineering degree from 2nd, 3rd & 4th year student's.

Researchers and professionals looking to enhance their skills in CFD and electronic thermal management.

Internship Benefits

- Gain in-depth knowledge of ANSYS ICEPAK for thermal and flow analysis.
- Build expertise in thermal management of electronics, a growing industry need.
- Develop a professional network in the field of electronic cooling.
- Enhance your resume with hands-on simulation experience.

How to Apply?

- Step 1:** Register online at <https://tinyurl.com/yc54e7bv>
- Step 2:** Submit your updated CV and a brief statement of interest.
- Step 3:** Pay the internship fee (details provided upon selection).
- Step 4:** Interview through online



Contact Us

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A++



Category 1
with 12B Status



(2024)
12th Ranked University



(2025) World Ranking
one among 46 Indian Universities



(2024) World Ranking
one among 91 Indian Universities



VERY GOOD
QS 4 Star Rated Globally



(2024) World Ranking
Ranked 5-7 in Indian Universities